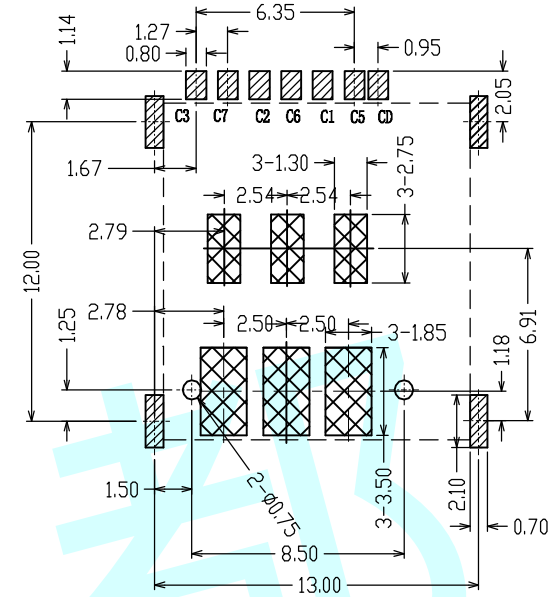
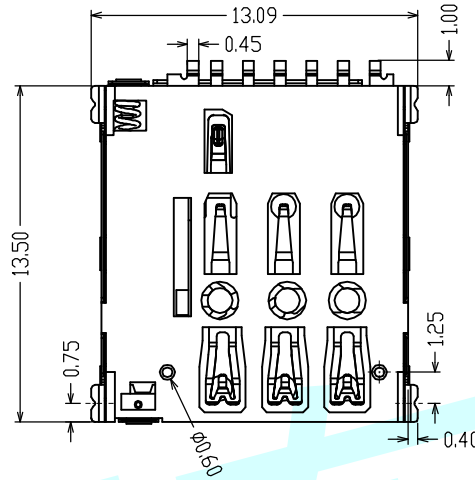
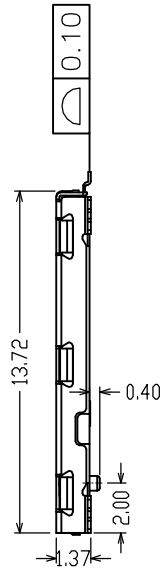
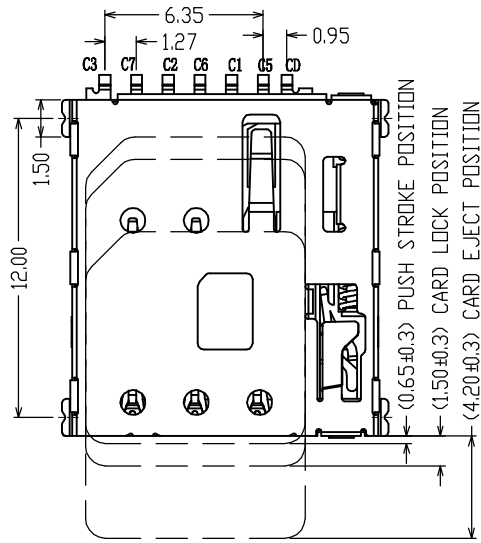
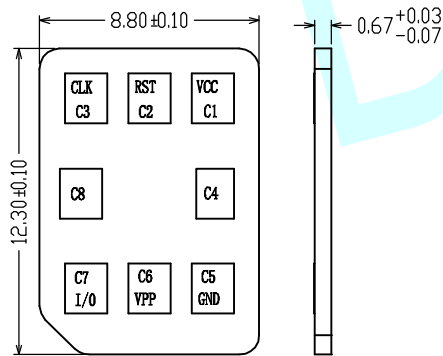
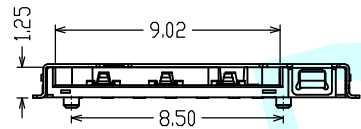


ROHS



RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ± 0.05

PAD KEEP OUT AREA



NANO SIM CARD

NOTES:

A. MATERIAL:

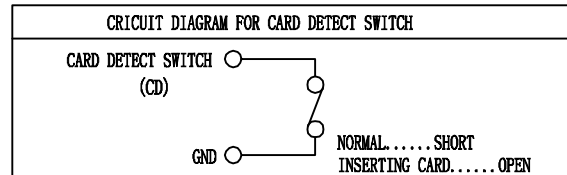
1. HOUSING: HI-TEMP. PLASIC UL 94V-0
2. CONTACT: COPPER ALLOY
3. SHELL: STAINLESS STEEL

B. PLATING :

1. CONTACT AREA: Au GOLD FLASH.
2. SOLDER AREA: AU GOLD FLASH.
3. UNDER PLATE: NICKEL.
4. SHELL: NICKEL PLATED OVER ALL.
5. SOLDER AREA: GOLD FLASH.

C. SPECIALITY:

1. Rated current: 1.0A
2. Rated voltage: 30V
3. Contact Resistance: 100mΩ MAX
4. Insulation Resistance: 1000MΩ MIN 500V DC
5. Dielectric withstanding voltage: 500V AC.
6. Solder ability: 260 \pm 5 $^{\circ}$ C, 30 \pm 10s.
7. Durability: 5000 Cycles Min.
8. Operating condition: Temperature -40 $^{\circ}$ C ~ +85 $^{\circ}$ C;
Humidity 80% R.H MAX



SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

APPROVALS		DATE	http://www.dongdudz.com	
DRAW:	ZRD	2017-12-6	TOLERANCE:	ANGLE:
CHECKED:	***	****	30 \geq	± 0.30
APPROVALS:	***	****	10 $^{\circ}$ 30	± 0.20
			5 $^{\circ}$ 10	± 0.15
			≤ 5	± 0.10
			$\pm 2^{\circ}$	

东都电子	
DONGDU ELECTRONICS	
MODEL:	CASSETTE
PART NO:	SIM-ZD-7PIN
UNIT :mm	SCALE:1:1
REV:	A
	PAGE:1/1